

ABSTRACT OF THE DISCLOSURE

A method and apparatus for at least partly covering at least one electronic component with compound, the apparatus being provided with a first mold half and a second mold half, the first mold half being moveable relative to the second mold half, while means are provided for placing an electronic component on a mold half for inclusion of this component in a mold cavity defined by the two mold halves, the first mold half being provided with a number of actuators with the aid of which the position of the first mold half relative to the second mold half is continuously and accurately regulable, while the distance between the two mold halves is continuously regulated and, if desired, adjusted during the two mold halves being moved towards each other and during their being held in a position when moved towards each other.

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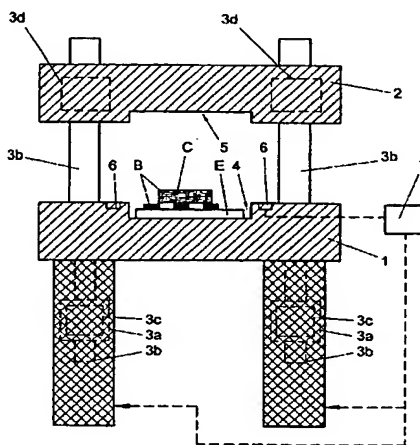
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(54) Title: METHOD AND APPARATUS FOR COMPLETELY OR PARTLY COVERING AT LEAST ONE ELECTRONIC COMPONENT WITH A COMPOUND



(57) **Abstract:** A method and apparatus for at least partly covering at least one electronic component with compound, the apparatus being provided with a first mold half and a second mold half, the first mold half being moveable relative to the second mold half, while means are provided for placing an electronic component on a mold half for inclusion of this component in a mold cavity defined by the two mold halves, the first mold half being provided with a number of actuators with the aid of which the position of the first mold half relative to the second mold half is continuously and accurately regulable, while the distance between the two mold halves is continuously regulated and, if desired, adjusted during the two mold halves being moved towards each other and during their being held in a position when moved towards each other.

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